

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Thomas, et al.

Docket No.: TI-29525.1A

Serial No.: TBD

Examiner: TBD

Filed: 10/28/2003

Art Unit: TBD

For: Flip-Chip Assembly of Protected Micromechanical Devices

Preliminary Amendment

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)
I hereby certify that this correspondence is being deposited with
the U.S. Postal Service as First Class Mail in an envelope addressed
to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-
1450 on

October 28, 2003.

Elizabeth Austin
Elizabeth Austin

Dear Sir:

Please enter the following amendments prior to examination of the instant application. The Commissioner is hereby requested and authorized to charge any fees necessary for the filing of this paper to Texas Instruments Incorporated deposit account no. 20-0668.